

TO86-SD1-AA05

ORv3 GPU Server - 8OU DP NVIDIA HGX™ B200



Key Features

- NVIDIA HGX™ B200
- 1.8TB/s GPU-to-GPU bandwidth with NVIDIA NVLink™ and NVSwitch™
- Dual Intel® Xeon® 6700/6500-Series Processors
- 8-Channel DDR5 RDIMM / MRDIMM, 32 x DIMMs
- Compatible with NVIDIA® BlueField®-3 DPUs and NVIDIA ConnectX®-7 NICs
- 2 x 10Gb/s LAN ports via Intel® X710-AT2
- 1 x M.2 slot with PCIe Gen5 x4 interface
- 8 x 2.5" Gen5 NVMe hot-swap bays
- 12 x FHHL PCIe Gen5 x16 slots
- 48V to 54V DC Bus Bar power solution

Specification

Dimensions	8OU (W537 x H380.5 x D853 mm)	Modular GPU	NVIDIA HGX™ B200 with 8 x SXM GPUs
Open Rack Version	ORv3	PCIe Expansion Slots	12 x FHHL PCIe Gen5 x16
Motherboard	MSJ4-GD0	Front I/O	1 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN
CPU	Intel® Xeon® 6 Processors - Intel® Xeon® 6700-Series Processors - Intel® Xeon® 6500-Series Processors Dual processor, TDP up to 350W	TPM	1 x TPM header (SPI), Optional TPM2.0 kit: CTM010 1 x PROt connector (only enabled on RoT SKU)
Socket	2 x LGA 4710 (Socket E2)	System Management	ASPEED® AST2600 Baseboard Management Controller GIGABYTE Management Console web interface
Chipset	System on Chip	System Fans	Motherboard: 4 x 92x92x38mm GPU tray: 12 x 92x92x76mm
Memory	8-Channel DDR5 RDIMM/MRDIMM, 32 x DIMMs [RDIMM] Up to 6400 MT/s (1DPC), 5200 MT/s (2DPC) [MRDIMM] Up to 8000 MT/s ^[1] ^[1] MRDIMMs are only supported with Intel® Xeon® 6 Processors with P-cores and in a 1DPC configuration.	Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
LAN	2 x 10Gb/s LAN (1 x Intel® X710-AT2), Support NCSI 1 x 10/100/1000 Mbps Management LAN	Packaging Content	1 x TO86-SD1-AA05 2 x CPU heatsinks 4 x Carriers
Storage	Front hot-swap: 8 x 2.5" Gen5 NVMe Internal M.2: 1 x M.2 (2280/22110), PCIe Gen5 x4	No. of Bus Bars	5 x 48V to 54V Bus Bar Connectors
		Ordering Part Numbers	6NTO86SD1UR000AA05*

